



IST and Accelaronix unveil industry's first IFPP at MWC26 with Tele2 IoT

Demonstrating secure final MNO profile injection at scale for single-SKU manufacturing.

CONNECTIVITY

POSTED ON 02.27.26

IDEMIA Secure Transactions (IST), together with Accelaronix and Tele2 IoT, will demonstrate an early implementation of **In-Factory Profile Provisioning (IFPP)**—a future-ready solution designed to simplify and secure connectivity provisioning in manufacturing environments, ready to integrate post-quantum algorithms.

The joint demonstration showcases how OEMs can securely inject final mobile network operator (MNO) profiles directly in their factory at scale, enabling true single-SKU manufacturing for devices with eSIM or iSIM technologies. This industry-first demonstration also confirms the technical feasibility of IFPP ahead of full GSMA standardization SGP.42.

IFPP as a catalyst for massive scale deployment

Today's field-based connectivity tailoring forces OEMs to manage multiple SIM and device SKUs, navigate complex localization, and rely on risky in-field profile downloads. The result is increased logistics costs and limited factory testing, especially for constrained IoT devices.

The demonstrated IFPP solution removes these constraints. Devices can now be manufactured as a single global SKU and personalized with the appropriate MNO profile at the end of the production line, just before deployment in an environment that does not require GSMA certification.

Bridging the gap toward future-ready eSIM architecture

The solution is based on the GSMA SGP.41 architecture and requirements, ensuring consistency with the industry's framework for IFPP. It is ready for deployment today, as it builds on existing eSIM IoT infrastructure and established operational processes already in place across the ecosystem. This enables OEMs to move forward immediately while remaining fully prepared to upgrade seamlessly to SGP.42 once the detailed technical specification becomes available.

Beyond standards alignment and readiness, the solution has been designed with long-term security in mind. IST's quantum-safe solution protects sensitive MNO credentials handled in factory environments and supports fully offline factory operations, without requiring continuous connectivity to external servers. IFPP is eSIM form factor agnostic, making it applicable across a wide range of use cases, from smart meters and asset trackers to automotive.

Live demonstrations

Through partnerships with Acceleronix, a leading global end-to-end IoT solution provider, and Tele2 IoT, a key MNO in the IoT space, IDEMIA Secure Transactions reinforces its role as a trusted orchestrator of secure connectivity solutions. As part of the live demonstrations, IST will jointly offer with Acceleronix and Tele2 IoT, an early access test kit that will enable OEMs and ecosystem partners to evaluate IFPP in their own environments for large-scale adoption.

Participate in the live demonstration at the following locations to obtain your kit and speak directly with company experts to explore how IFPP can transform your manufacturing strategy:

- **MWC Barcelona '26:** GSMA Roundtable for PQC implementations at CC2.5 GSMA Insights Hub, Hall 2
- **MWC Barcelona '26:** Hall 5 Stand 5A19 at Quectel booth & Hall 7 Stand 7A41 at Tele2 IoT booth
- **Embedded World Nuremberg (March 10-12, 2026):** 3A-530 at Quectel booth

IFPP marks a turning point for OEMs to significantly simplify and optimize the manufacturing process for connected devices. By combining our connectivity solutions expertise, particularly eSIM SGP.32, our architecture built to adopt post-quantum algorithms and cryptoagility capabilities, together with Acceleronix's factory orchestration, and Tele2's IoT connectivity leadership, we are proving that in-factory provisioning is not theoretical: it is live, scalable, and ready for industrial adoption.

Philippe de Oliveira, Senior VP Auto & IoT Connectivity Services, IDEMIA Secure Transactions

Acceleronix is leading the industry with our SGP.32 enabled solution, SIM orchestration, and pan-regional IoT connectivity. This new IFPP Early Access Program demonstrates our commitment to eSIM technology and reflects our focus on streamlining the IoT device and connectivity lifecycle to support scalable IoT solutions. I'm delighted to have collaborated with IDEMIA Secure Transactions and Tele2 to create this partnership and we're proud to bring it to MWC26, to showcase how IFPP simplifies device provisioning at scale, reduces operational risk and enables out-of-the-box connectivity as devices leave the production line.

Gal Olshinka, Director, Acceleronix

Tele2 IoT is proud to collaborate with IDEMIA Secure Transactions and Acceleronix to bring this IFPP Early Access Program to life. By combining our managed global IoT connectivity and provisioning capabilities with in-factory profile provisioning, we're enabling OEMs to ship devices that are ready to connect straight from the factory. This approach significantly simplifies the IoT lifecycle, reduces operational complexity, and supports scalable, secure deployments worldwide.

Onur Kasaba, Managing Director, Tele2 IoT